

2835 Full Spectrum Datasheet





Features:

Slim Size SMD Package: Design Flexibility
High Lumen Output and High Efficacy
Stable Performance & Great CCT Unity
Full Spectrum 380-850nm
High Forward Voltage 9V, 18V, 36V Available
Environmental Friendly; ROHS Compliance
Customized Service Available

Applications:

LED Module, Illuminated Advertising
Tube Light, Panel Light, Ceiling Lamp and other LED Indoor Lights
Flood Light, High Bay Light, Tunel Light and other LED Outdoor Lights
LED Aquarium Light, LED Plant Growing Light..



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PRODUCT NAMING RULES

LKL	XXXX	FSXX	Х	Х	XXX	
LKL	Туре	Color	Chip QTY	Beam Angle	Brightness	
LEKOLED	2835	FS01: Full Spectrum 1	1: 1EA	0: 120°/140°	15: 15-18LM	
		FS03: Full Spectrum 3	2: 2EA		30: 30-32LM	
		FS11: Full Spectrum 11	3: 3EA			

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CHARACTERISTICS

Parameter	Unit	Min	Typical	Max
Power Dissipation 1	mW		200	
Power Dissipation 2	mW		504	
Forward Current 1	mA		60	
Forward Current 2	mA		150	
Forward Voltage	V	2,8		3,4
Color Rendering Index	Ra		90	
Beam Angle 201/2	deg.		120	
Reverse Current	uA			10
Reverse Voltage	V			5
Operating Temperature Top	$^{\circ}\!$	-40		+60
Storage Temperature Tst	$^{\circ}\! \mathbb{C}$	-40		+85
Testing Point Tc	$^{\circ}\!$			55
Junction Temperature Tj	$^{\circ}\!\mathrm{C}$			120
Reverse Current (Vr=5V) Ir	uA			5
Related thermal resistance Rj-c	°C/W		8	
ESD (HBM)	V			2000
Reflow Soldering (Lead-Free) ST	$^{\circ}\!\mathbb{C}$			260



LUMINOUS FLUX CHARACTERISTIC

Specifications (IF=60mA, Tc=25 $^{\circ}$ C)

Light Color	Color Temperature (K)	CRI	0.2W, 3V @60mA LM	Model No.
Full Spectrum 01	1200-1300K	/	30-32	LKL-2835FS011030
Full Spectrum 03	2900-3000K	90	15-18	LKL-2835FS031015
Full Spectrum 04	6800-7000K	90	15-18	LKL-2835FS041015
Full Spectrum 05	2900-3000К	90	15-18	LKL-2835FS031015
Full Spectrum 07	1700-1800K	/	30-32	LKL-2835FS071030
Full Spectrum 09	1200-1300K	/	30-32	LKL-2835FS091030
Full Spectrum 11	4700-4900K	/	30-32	LKL-2835FS111030
Full Spectrum 13	4200-4400K	90	15-18	LKL-2835FS131015
Full Spectrum 15	2000-2200K	/	30-32	LKL-2835FS151030
Full Spectrum 16	100000K	/	30-32	LKL-2835FS161030

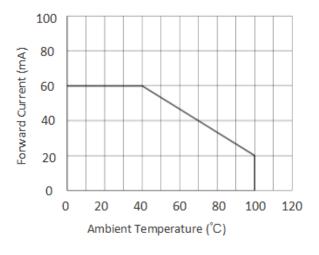
Specifications (IF=150mA, Tc=25 $^{\circ}$ C)

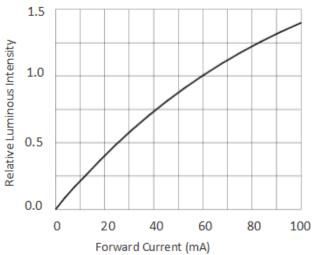
Light Color	Color Temperature (K)	CRI	0.5W, 3V @150mA LM	Model No.
Full Spectrum 01	1200-1300K	/	50-60	LKL-2835FS012050
Full Spectrum 03	2900-3000K	90	30-40	LKL-2835FS032030
Full Spectrum 04	6800-7000K	90	30-40	LKL-2835FS042030
Full Spectrum 05	2900-3000K	90	30-40	LKL-2835FS032030
Full Spectrum 07	1700-1800K	/	50-60	LKL-2835FS072050
Full Spectrum 09	1200-1300K	/	50-60	LKL-2835FS092050
Full Spectrum 11	4700-4900K	/	50-60	LKL-2835FS112050
Full Spectrum 13	4200-4400K	90	30-40	LKL-2835FS132030
Full Spectrum 15	2000-2200K	/	50-60	LKL-2835FS152050
Full Spectrum 16	100000K	/	50-60	LKL-2835FS162050

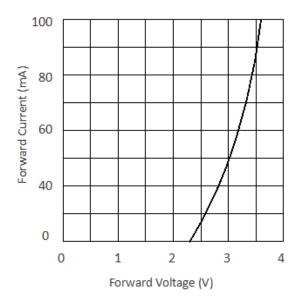


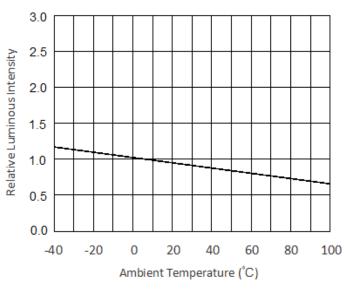
TYPICAL CHARACTERISTIC CURVES

IF=60mA





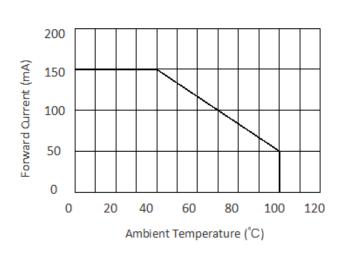


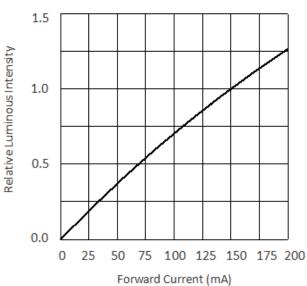


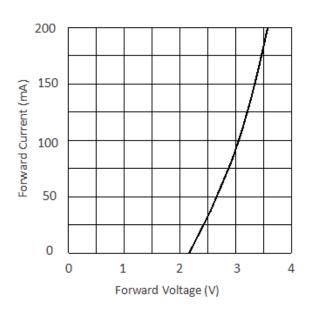


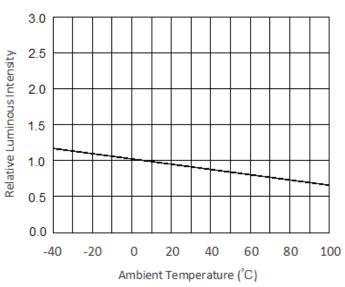
TYPICAL CHARACTERISTIC CURVES

IF=150mA



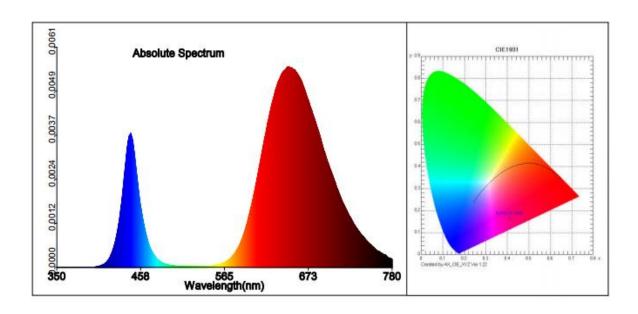








NO. 1



Test parameter:

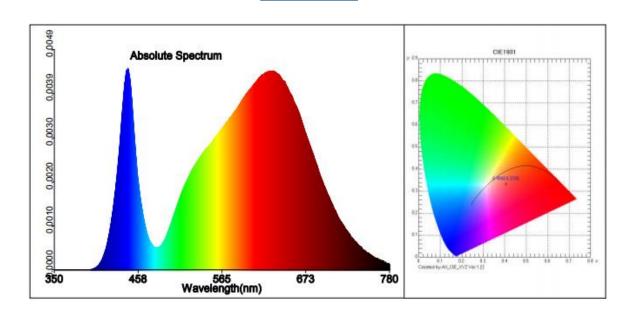
E= 49.0 lx	E(fc)=4.54948 fc		
CIE x= 0.4103 Tc=1211 K Pur=55.8 % Duv=0.12108	CIE y= 0.1640 Lp=661.0 nm Ratio_R=78.6 %	CIE u'=0.3957 HW=94.3 nm Ratio_G=13.8 %	CIE v'=0.3559 Ld=610.2 nm Ratio_B=7.6 %
Ra=-17.4 R4= 16 R8= 44 R12=-515	R1= 57 R5= 12 R9= 54 R13= 13	R2=-18 R6=-121 R10=-155 R14= -4	R3=-98 R7=-31 R11= 40 R15= 51
SDCM= 0.2()			

SDCM= 0.2() White Class:OUT

E1=0.57817 W/m2 E2=0.73919 W/m2 PPFD=2.9661 μmol/(m·s) Ech-A=0.15406 W/m2 Ech-B=0.1342 W/m2 Ef=0.16144 W/m2 Ep=0.52529 Wphyto/m2 Erb_Ratio=3.8317 PPFDf=9.4289Ε-001 μmol/(m2·s)



NO. 3



Test parameter:

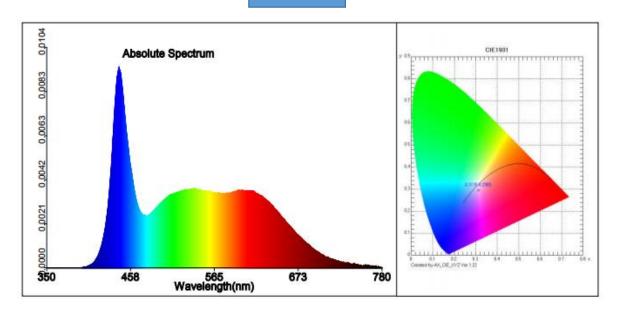
E= 220.7 lx	E(fc)=20.5151 fc		
CIE x= 0.4068 Tc=2910 K Pur=22.1 % Duv=-0.02696	CIE y= 0.3336 Lp=449.0 nm Ratio_R=26.4 %	CIE u'=0.2629 HW=26.2 nm Ratio_G=71.0 %	CIE v'=0.4851 Ld=609.8 nm Ratio_B=2.7 %
Ra=92.1 R4= 87 R8= 91 R12= 89	R1= 97 R5= 95 R9= 92 R13= 96	R2= 95 R6= 92 R10= 90 R14= 94	R3= 92 R7= 88 R11= 85 R15= 94
SDCM= 0.3()			

SDCM= 0.3() White Class:OUT

E1=0.86312 W/m2 Ech-A=0.12159 W/m2 Eb=0.16281 W/m2 Ep=0.77237 Wphyto/m2	E2=0.96281 W/m2 Ech-B=0.13853 W/m2 Ey=0.27285 W/m2 Erb_Ratio=2.6286	PPFD=4.2011 µmol/(m·s) Ef=0.099952 W/m2 Er=0.42796 W/m2
PPFDf=5.8502E-001 µmol/(m2·s)		



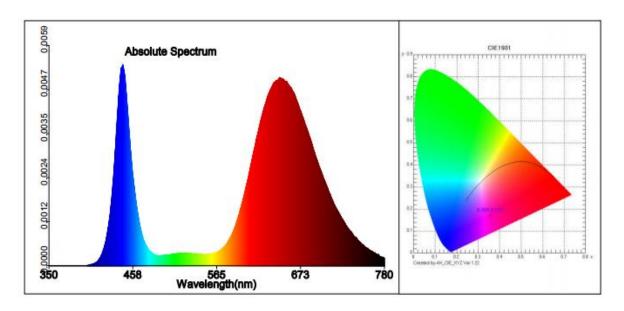
NO. 4



E= 284.1 lx	E(fc)=26	.4054 fc		
CIE x= 0.3130 Tc=6816 K Pur=11.6 % Duv=-0.01470	CIE y= 0 Lp=447.0 Ratio_R:	0 nm	CIE u'=0.2110 HW=26.5 nm Ratio_G=76.2 %	CIE v'=0.4499 Ld=448.4 nm Ratio_B=6.4 %
Ra=90.3 R4= 88 R8= 90 R12= 79	R1= 90 R5= 92 R9= 73 R13= 91		R2= 94 R6= 89 R10= 89 R14= 91	R3= 86 R7= 93 R11= 86 R15= 86
SDCM= 0.3() White Class:OUT				
E1=1.0696 W/m2 Ech-A=0.078194 W/m2 Eb=0.37545 W/m2 Ep=0.90075 Wphyto/m2 PPFDf=2.2503E-001 µmol/(m2·s)		E2=1.1077 W/m2 Ech-B=0.11615 W/m2 Ey=0.38903 W/m2 Erb_Ratio=0.8146		PPFD=4.858 µmol/(m·s) Ef=0.038201 W/m2 Er=0.30584 W/m2



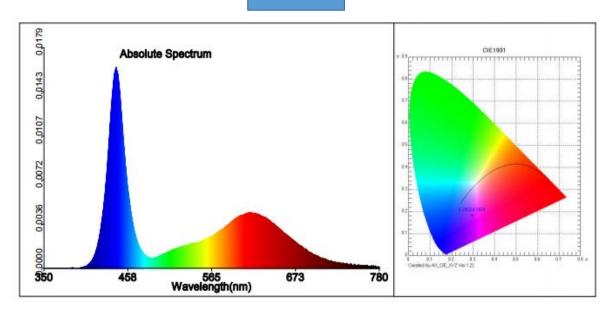
NO. 5



E= 66.7 lx	E(fc)=6.197	713 fc				
CIE x= 0.3581 Tc=1768 K Pur=49.2 % Duv=-0.12360	CIE y= 0.17 Lp=449.0 n Ratio_R=57	m	CIE u'=0.3302 HW=23.7 nm Ratio_G=34.2 %		CIE v'=0.3551 Ld=610.2 nm Ratio_B=8.6 %	
Ra=2.0 R4= 75 R8= 53 R12=-334	R1= 9 R5=-25 R9=-65 R13=-21		R2=-18 R6=-91 R10=-145 R14= 41		R3=-19 R7= 31 R11= 46 R15= -9	
SDCM= 0.2() White Class:OUT						
E1=0.62799 W/m2 Ech-A=0.13376 W/m2 Eb=0.16913 W/m2 Ep=0.55871 Wphyto/m2 PPFDf=8.4310E-001 µmol/	E E	2=0.77204 W/m ch-B=0.11571 V y=0.042269 W/c rb_Ratio=2.464	N/m2 m2	Ef=0.14	3.1203 µmol/(m·s) 1442 W/m2 1674 W/m2	



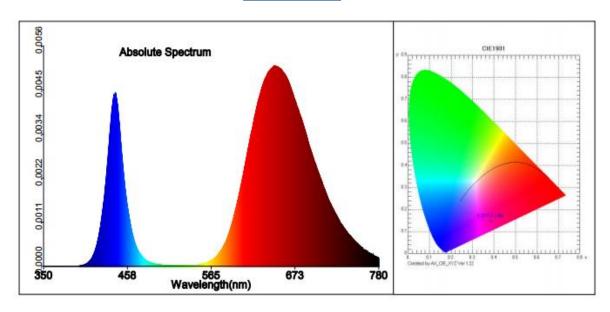
NO. 7



E= 202.8 lx	E(fc)=18.8464 fc		
CIE x= 0.2958 Tc=100000 K Pur=42.4 % Duv=-0.08083	CIE y= 0.1834 Lp=447.0 nm Ratio_R=28.6 %	CIE u'=0.2567 HW=24.9 nm Ratio_G=63.2 %	CIE v'=0.3581 Ld=380.0 nm Ratio_B=8.2 %
Ra=41.2 R4= 34 R8= 11 R12= 52	R1= 15 R5= 33 R9=-191 R13= 21	R2= 52 R6= 48 R10= 30 R14= 67	R3= 56 R7= 80 R11= 23 R15=-17
SDCM= 0.2() White Class:OUT			
E1=1.144 W/m2 Ech-A=0.094375 W/m2 Eb=0.53494 W/m2 Ep=0.9637 Wphyto/m2 PPFDf=3.2785E-001 µmo	Ech-B=0 Ey=0.22 Erb_Rat	004 W/m2 0.12661 W/m2 2667 W/m2 tio=0.71572	PPFD=5.1242 µmol/(m·s) Ef=0.056532 W/m2 Er=0.38287 W/m2



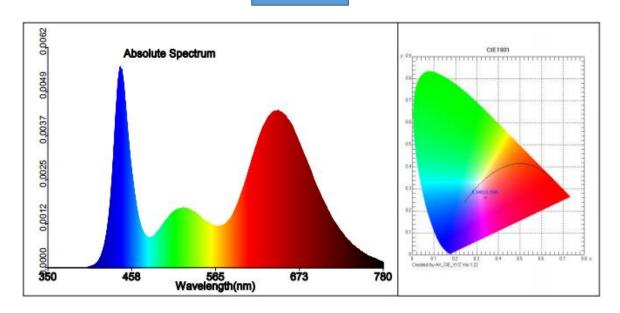
NO. 9



E= 47.9 lx	E(fc)=4.4	45347 fc			
CIE x= 0.3837 Tc=1289 K Pur=57.5 % Duv=0.13714	CIE y= 0 Lp=660.0 Ratio_R:	0 nm	CIE u'=0.3821 HW=95.7 nm Ratio_G=15.1 %	Ĺ	d=610.2 nm datio_B=8.0 %
Ra=-24.6 R4= 4 R8= 44 R12=-516	R1= 54 R5= 10 R9= 45 R13= 6		R2=-27 R6=-132 R10=-172 R14=-11	R	23=-110 27=-40 211= 27 215= 40
SDCM= 0.1() White Class:OUT E1=0.56991 W/m2 Ech-A=0.13219 W/m2 Eb=0.1394 W/m2 Ep=0.51337 Wphyto/m2 PPFDf=8.6331E-001 µmo	ol/(m2·s)	E2=0.71745 W/r Ech-B=0.11071 Ey=0.014353 W Erb_Ratio=2.980	W/m2 //m2	Ef=0.147	.8754 µmol/(m·s) '91 W/m2 '26 W/m2



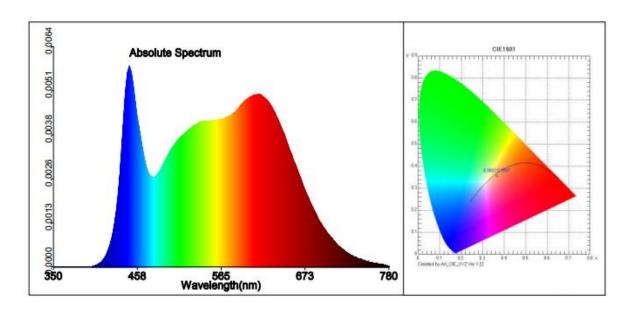
NO. 11



E= 132.1 lx	E(fc)=12	.2804 fc		
CIE x= 0.3400 Tc=4710 K Pur=22.3 % Duv=-0.05329	CIE y= 0 Lp=447.0 Ratio_R=	0 nm	CIE u'=0.2503 HW=24.7 nm Ratio_G=64.2 %	CIE v'=0.4298 Ld=610.2 nm Ratio_B=6.2 %
Ra=45.8 R4= 35 R8= -4 R12= 43	R1= 30 R5= 35 R9=-145 R13= 35		R2= 62 R6= 60 R10= 31 R14= 83	R3= 79 R7= 69 R11= 25 R15= 2
SDCM= 0.3() White Class:OUT				
E1=0.72767 W/m2 Ech-A=0.11241 W/m2 Eb=0.19437 W/m2 Ep=0.63509 Wphyto/m2 PPFDf=6.8427E-001 μmol/(m2·s)		E2=0.84431 W/m2 Ech-B=0.10372 W/m2 Ey=0.15306 W/m2 Erb_Ratio=1.9577		PPFD=3.5175 µmol/(m·s) Ef=0.11696 W/m2 Er=0.38052 W/m2



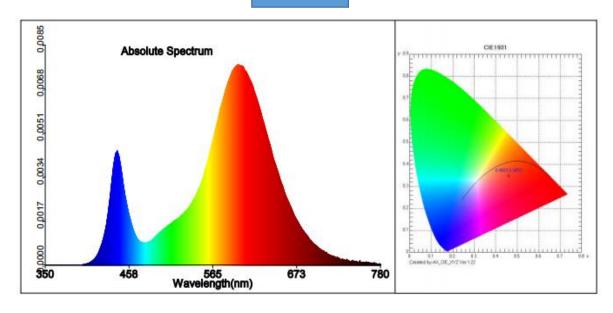
NO. 13



E= 333.1 lx	E(fc)=30	.9572 fc		
CIE x= 0.3662 Tc=4277 K Pur=16.9 % Duv=-0.00526	CIE y= 0 Lp=452.0 Ratio_R:	0 nm	CIE u'=0.2237 HW=34.5 nm Ratio_G=74.9 %	CIE v'=0.4903 Ld=582.3 nm Ratio_B=5.0 %
Ra=97.3 R4= 99 R8= 97 R12= 79	R1= 98 R5= 98 R9= 95 R13= 98	ı	R2= 98 R6= 95 R10= 98 R14= 98	R3= 97 R7= 97 R11= 97 R15= 97
SDCM= 0.4() White Class:OUT E1=1.1474 W/m2 Ech-A=0.094271 W/m2 Eb=0.27442 W/m2 Ep=0.99299 Wphyto/m2 PPFDf=3.2254E-001 µmo	ol/(m2·s)	E2=1.2016 W/m Ech-B=0.12282 Ey=0.44644 W/r Erb_Ratio=1.55	W/m2 m2	PPFD=5.4105 µmol/(m·s) Ef=0.054369 W/m2 Er=0.42738 W/m2



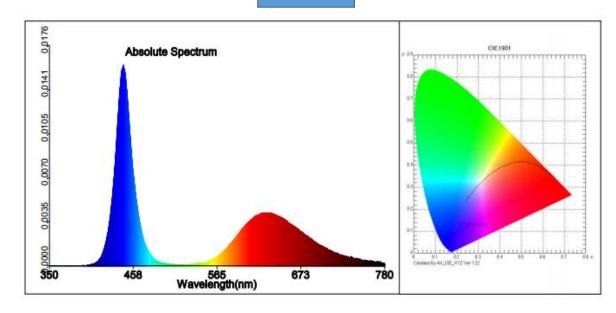
NO. 15



E= 307.9 lx	E(fc)=28	.6185 fc			
CIE x= 0.4603 Tc=2197 K Pur=42.9 % Duv=-0.02341	CIE y= 0 Lp=609.0 Ratio_R:	0 nm	CIE u'=0.2936 HW=92.7 nm Ratio_G=66.2 %	Ld=60	'=0.5013 00.4 nm _B=2.3 %
Ra=75.2 R4= 68 R8= 43 R12= 82	R1= 80 R5= 82 R9= 0 R13= 85		R2= 96 R6= 90 R10= 95 R14= 89	R3= 7 R7= 6 R11= R15=	65 67
SDCM= 0.3() White Class:OUT					
E1=1.048 W/m2 Ech-A=0.091626 W/m2 Eb=0.1642 W/m2 Ep=0.95354 Wphyto/m2 PPFDf=2.1342E-001 μmo	E2=1.0841 W/m Ech-B=0.14551 Ey=0.36369 W/n Erb_Ratio=3.173		W/m2 m2	PPFD=5.1070 Ef=0.0363 W Er=0.52102 V	/m2



NO. 16



E= 92.5 lx	E(fc)=8.5	59386 fc			
CIE x= 0.2735 Tc=100000 K Pur=64.4 % Duv=-0.14787	CIE y= 0 Lp=449.0 Ratio_R:	0 nm	CIE u'=0.2937 HW=23.9 nm Ratio_G=30.8 %		CIE v'=0.2560 Ld=380.0 nm Ratio_B=17.4 %
Ra=-67.8 R4=-11 R8=-50 R12=-188	R1=-85 R5=-66 R9=-455 R13=-11		R2=-111 R6=-110 R10=-357 R14= 3		R3=-114 R7= 5 R11=-38 R15=-166
SDCM= 0.1() White Class:OUT					
E1=0.92845 W/m2 Ech-A=0.09374 W/m2 Eb=0.4968 W/m2 Ep=0.77968 Wphyto/m2 PPFDf=5.5020E-001 µmo	ol/(m2·s)	E2=1.0241 W/m Ech-B=0.10334 Ey=0.054004 W Erb_Ratio=0.76	W/m2 //m2	Ef=0.0	=4.1796 µmol/(m·s) 095869 W/m2 37792 W/m2



RELIABILITY TESTS

Test Items	Test Conditions	Sample QTY	Ac/Re
Aging Tost	IF=60-150mA, Ta=25 [°] C x6000hrs	22	0/1
Aging Test	IF=60-150mA, Ta=85 [°] C x6000hrs	22	0/1
High Temperature Storage	100℃ x1000hrs	22	0/1
Low Temperature Storage	-40°C x1000hrs	22	0/1
High Temp & Humidity	IF=60-150mA, 85 °C , 85% RH for 6000hrs	22	0/1
Temperature Shock	-40°Cx30 min & +100°Cx30 min, 100cycle	22	0/1
ESD(HBM)	2000V HBM/ 1 Time	10	0/1

Criteria for Judging LED Failure (Tc= 25°C)

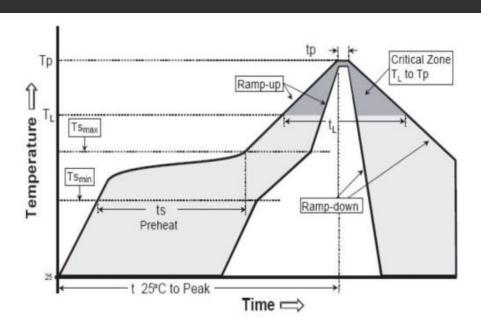
Items	Symbol	Test Conditions	Criteria for Judging LED Failure
Forward Voltage	VF	IF=60-150mA	>U x 1.1
Reverse Current	IR	VR=5V	IR>/= 10μA
Lumen	ФV	IF=60-150mA	<s 0.7<="" td="" x=""></s>

U refers to max value; S refers to initial value.



TYPICAL CHARACTERISTIC CURVES

REFLOW SOLDERING PROFILE

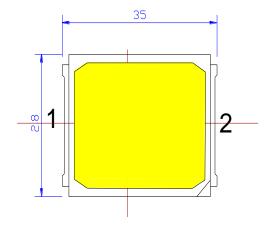


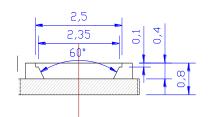
Profile Features	Lead-free solder	Lead solder	Soldering by Manual
Ramp-up Speed(Ts max to Tp)	3 °C/ second max.	3 °C/ second max.	
Preheat: Min. Temperature(Tsmin)	150 °C	100 °C	
Preheat: Max.Temperature(Tsmax)	200 °C	150 °C	
Preheat: Time (tsmin to tsmax)	60~180 seconds	60~120 seconds	
Temperature to Keep: (TL)	217 °C	183 °C	Max. temperature: 350°C
Time to Keep: (tL)	60~150 seconds	60~150 seconds	3 seconds/1 time
Peak Temperature (Tp)	260 °C	215 °C	
temperature	20~40 seconds	10~30 seconds	
Ramp-down Speed	6°C/ second max.	6°C/ second max.	
Time to the peak Temperature	8 minutes max.	6 minutes max.	

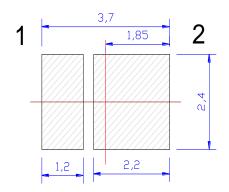


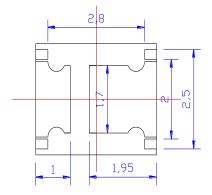
DIMENSIONS

Unit: mm









Notes:

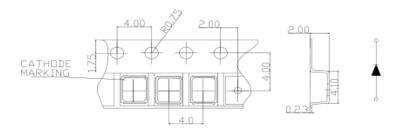
*All dimensions are in millimeters.(tolerance:±0.2mm)

*The appearance and specifications of the product may be changed for improvement without notice.

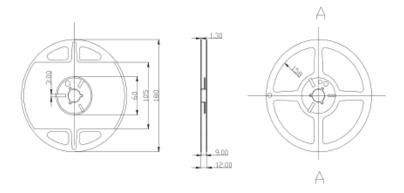


PACKAGING

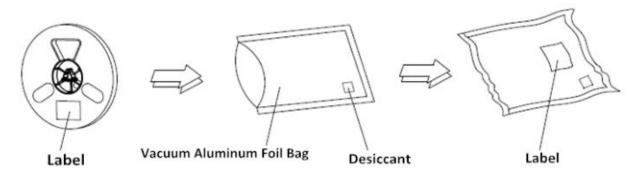
Tape Specifications (Units: mm)



Reel Dimensions



Moisture Resistant Packaging





PRECAUTIONS

Storage

- 1. Moisture proof and anti-electrostatic package with moisture absorbent material is used, to keep moisture to aminimum.
- 2. Before opening the package, the product should be kept at 30°C or less and humidity less than 60% RH, and beused within a year.
- 3. After opening the package, the product should be stored at 30° C or less and humidity less than 10%RH, and besoldered within 24 hrs (1day). It is recommended that the product be operated at the workshop condition of 30° C or less and humidity less than 60%RH.
- 4. If the moisture absorbent material has fade away or the LEDs have exceeded the storage time, baking treatment should be performed based on the following condition: (80±5) ℃ for 24 hours.

Static Electricity

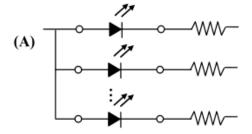
- 1. Static electricity or surge voltage damages the LEDs. Damaged LEDs will show some unusual characteristic such as the forward voltage becomes lower, or the LEDs do not light at the low current. even not light.
- 2. All devices, equipment and machinery must be properly grounded. At the same time, it is recommended that wrist bands or anti-electrostatic gloves, anti-electrostatic containers be used when dealing with the LEDs.

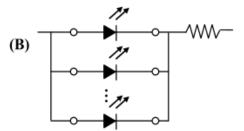
Vulcanization

LED curing is due to sulfur being in bracket and the +1 price of silver in the chemical reaction generated Ag2S in the process. It will lead to the capacity of reflecting of silver layer reducing, light color temperature drift and serious decline, seriously affecting the performance of the product. So we should take corresponding measures to avioding vulcanization, such as to avoid using sulphur volatile substances and keeping away from high sulphur content of the material.

Design Consideration

- 1. In designing a circuit, the current through each LED must not exceed the absolute maximum rating specified for each LED. In the meanwhile, resistors for protection should be applied, otherwise slight voltage shift will cause big current change, burn out may happen.
- 2. It is recommended to use Circuit A which regulates the current flowing through each LED rather than Circuit B.
 When driving LEDs with a constant voltage in Circuit B, the current through the LEDs may vary due to the variation in Forward Voltage (VF) of the LEDs. In the worst case, some LED may be subjected to stresses in excess of the Absolute Maximum Rating.





3. Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Color changed and so on. Please consider the heat generation of the LEDs when making the system design.



PRECAUTIONS

Safety Advice For Human Eyes

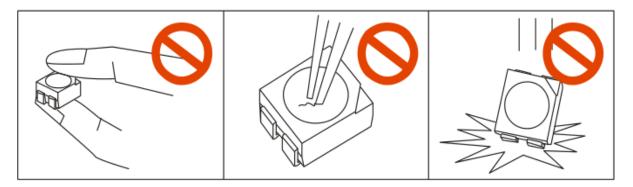
Viewing direct to the light emitting center of the LEDs, especially those of great Luminous Intensity will cause great hazard to human eyes. Please be careful.

The safe temperature for LEDs working

The high temperature will make the LEDs' Luminous Intensity decreased radically, if LEDs worked in hoteyes. Please be careful. environment for a long time, they will be disabled easily. When LEDs are working in a closed array, we suggest that the LEDs' surface temperature should be lower than 55°C and the legs' temperature should be lower than 75°C.

Others

1. When handling the product, touching the encapsulant with bare hands will not only contaminate its surface, but also affect on its optical characteristics. Excessive force to the encapsulant might result in catastrophic failure of the LEDs due to Die breakage or wire deformation. For this reason, please do not put excessive stress on LEDs, especially when the LEDs are heated such as during Reflow Soldering.



2. The epoxy resin of encapsulant is fragile, so please avoid scratch or friction over the epoxy resin surface. While handling the product with tweezers, do not hold by the epoxy resin, be careful.